

**Automotive Qualification Results Summary  
for ADSP-SC57x and ADSP-2157x Products**

<b>QUALIFICATION RESULTS</b>			
<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>RESULTS</b>
Solder Heat Resistance (SHR) <sup>1</sup>	JEDEC/IPC <i>J-STD-020</i>	3x10	<b>Pass</b>
Latch-Up <sup>2</sup>	JEDEC <i>JESD78</i>	1x18	<b>Pass +/-200mA</b>
Electrostatic Discharge <i>Human Body Model(ESD-HBM)<sup>2</sup></i>	ESDA/JEDEC <i>JS-001</i>	1x18	<b>Pass +/-2000V</b>
Electrostatic Discharge <i>Field-Induced Charged Device Model(ESD-FICDM)<sup>2</sup></i>	ESDA/JEDEC <i>JS-002</i>	1x15	<b>Pass<sup>3</sup> +/-750V</b>

<sup>1</sup>These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 1000 cycles with results within specification limits.

<sup>2</sup>Pre- and post-stress electrical test was performed at room and hot temperatures.

<sup>3</sup>Passing level for FICDM is +/-750 V for 400 CSP BGA. Passing level for FICDM is +/-500 all pins and +/-700 corner pins for 176 LQFP-EP and meets AEC Q100 requirements.